

3GPP TSG SA#8
Düsseldorf, Germany, 26 -28 June, 2000

SP 000311

Source: TSG RAN
To: TSG SA, S1, SMG2

**Title: LS on interworking of low chiprate TDD with GSM,
high chiprate TDD and FDD.**

TSG RAN has started work on the low chiprate TDD, and will design the low chiprate TDD to allow interworking with GSM, high chiprate TDD and FDD.

TSG RAN will also make changes to the high chiprate TDD and FDD part of its specifications to allow the interworking with low chiprate TDD.

TSG SA is requested to include their requirements on interworking of low chiprate TDD with GSM, high chiprate TDD and FDD in the relevant SA specifications.

TSG GERAN/ETSI SMG2 is requested to include the interworking with low chiprate TDD in the GERAN specification for R00.